

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16388
1.3 Title of PCN	ST Shenzhen (China) assembly site and HHgrace (China) Diffusion site additional source for STM32H74x and STM32H75x listed products in LQFP 14x14 packages.
1.4 Product Category	STM32H742x, STM32H743x, STM32H750x and STM32H753x
1.5 Issue date	2026-07-07

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ST Shenzhen (China), HHGrace (China)

4. Description of change

	Old	New
4.1 Description	Current assembly sites (depending on package size) with Crolles Diffusion source: - AMKOR ATP (Philippine) Gold wire, - AMKOR ATP (Philippine) Copper Palladium wire, - ASE Kaohsiung (Taiwan) Copper Palladium wire , - MUAR (Malaysia) Copper Alloy wire , You may refer to 16388_Additional information.pdf document for further details.	Current assembly sites (depending on package size) with Crolles Diffusion source: - AMKOR ATP (Philippine) Gold wire, - AMKOR ATP (Philippine) Copper Palladium wire, - ASE Kaohsiung (Taiwan) Copper Palladium wire , - MUAR (Malaysia) Copper Alloy wire , Additional assembly site with HHGrace new Diffusion Source for extended capacity: - ST Shenzhen (China) Copper Alloy wire.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact on Form, Fit or Function	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST General Purpose and Automotive Microcontrollers division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Change is visible on the marking - Back-End Assembly Site code: • 7B : AMKOR ATP (Philippines) • AA : ASE KaoHsiung (Taiwan) • 99 : ST Muar (Malaysia) • GK : ST Shenzhen (China) New Assembly site - Diffusion plant code WX: • VQ : ST Crolles 300 (France) • Y5 : HHGrace WuXi (China) Fab 7 New Diffusion site • 2E : HHGrace WuXi (China) Fab 9 New Diffusion site Please refer to PCN 16388_Additional information.pdf document for further details.
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7. Timing / schedule	
7.1 Date of qualification results	2026-09-16
7.2 Intended start of delivery	2026-09-16
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	16388 MDRF-GPAM-RER2613 PCN16388-STShz add srce STM32H74x-H75x LQ14 - Reliab plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-07-07

9. Attachments (additional documentations)
16388 Public product.pdf 16388 MDRF-GPAM-RER2613 PCN16388-STShz add srce STM32H74x-H75x LQ14 - Reliab plan.pdf 16388 _Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H743VIT6	
	STM32H743VIT6TR	
	STM32H750VBT6	
	STM32H750VBT6TR	

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